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Harris

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Warren M. Farnworth

Serial No.: 10/043,468

Filed: January 10, 2002

For: METHOD OF FORMING
OVERMOLDED CHIP SCALE PACKAGE
AND RESULTING PRODUCT

Confirmation No.: 7094

Examiner: K. Nguyen

Group Art Unit: 2823

Attorney Docket No.: 2269-3085.4US
(96-1033.04/US)

CERTIFICATE OF MAILING

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AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed March 14, 2003, the three-month shortened statutory period for response to which expires on June 16, 2003, since June 14, 2003 fell on a Saturday.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.